PC452

Compact Surface Mount, High Collector emitter Voltage Type Photocoupler

■ Features

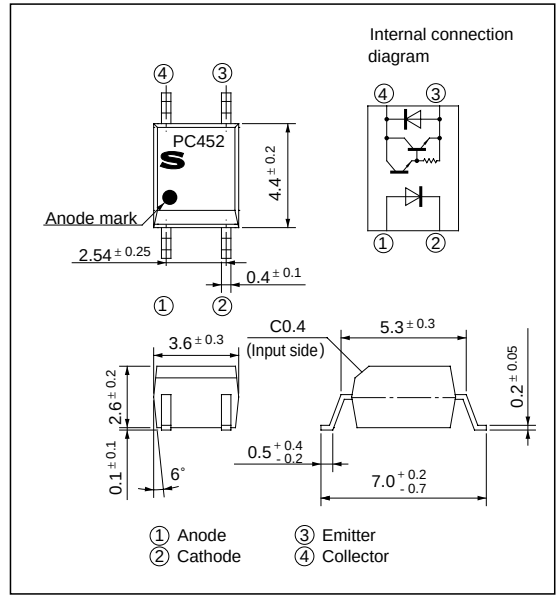
1. Mini-flat package
2. High collector-emitter voltage
   (V_{CEO} : 300V)
3. High current transfer ratio
   (CTR : MIN. 1 000% at I_F = 1mA, V_{CE} = 2V)
4. High isolation voltage between input and output
   (Viso : 3 750 V_{rms})

■ Applications

1. Telephone sets
2. Copiers, facsimiles
3. Interfaces with various power supply cir-
   cuits, power distribution boards
4. Hybrid substrates which reguire high
   density mounting

■ Outline Dimensions

(Unit : mm)



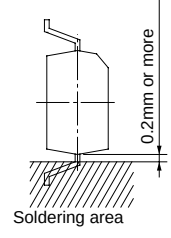
■ Package Specifications

Model No.	Package specifications	Diameter of reel	Tape width
PC452	Taping package (Net : 3 000pcs.)	ϕ 370mm	12mm
PC452T	Taping package (Net : 750pcs.)	ϕ 178mm	12mm
PC452Z	Sleeve package (Net : 100pcs.)	-	-

■ Absolute Maximum Ratings

(Ta=25˚C)

Parameter		Symbol	Rating	Unit
Input	Forward current	I_F	50	mA
	Reverse voltage	V_R	6	V
	Power dissipation	P	70	mW
Output	Collector-emitter voltage	V_{CEO}	300	V
	Collector current (forward direction)	I_C	150	mA
	Emitter-collector voltage	V_{ECO}	0.1	V
	Collecotr power dissipation	P_C	150	mW
Total power dissipation		P_{tot}	170	mW
*1Isolation voltage		V_{iso}	3 750	V_{rms}
Operating temperture		T_{opr}	- 30 to + 100	˚C
Storage temperature		T_{stg}	- 40 to + 125	˚C
*2Soldering temperature		T_{sol}	260	˚C



*1 AC for 1 minute, 40 to 60% RH
*2 10 seconds or less, 0.2mm or more from the root of lead.

■ Electro-optical Characteristics

(Ta= 25˚C)

Parameter			Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input	Forward voltage		V_F	I_F = 10mA	-	1.2	1.4	V
	Reverse current		I_R	V_R = 4V	-	-	10	μA
	Terminal capacitance		C_t	V = 0, f = 1kHz	-	30	250	pF
Output	Collecor-emitter breakdown voltage		BV_{CEO}	I_F = 0, I_C = 0.1mA	300	-	-	V
	Collector dark current		I_{CEO}	V_{CE} = 200V, I_F = 0	-	-	2×10^{-7}	A
Transfer characteristics	Collector current		I_C	I_F = 1mA, V_{CE} = 2V	10	-	-	mA
	Collector-emitter saturation voltage		$V_{CE(sat)}$	I_F = 20mA, I_C = 100mA	-	-	1.2	V
	Isolation resistance		R_{ISO}	DC500V, 40 to 60% RH	5×10^{10}	10^{11}	-	Ω
	Floating capacitance		C_f	V = 0, f = 1MHz	-	0.6	1.0	pF
	Cut-off frequency		f_c	V_{CE} = 2V, I_C = 20mA, R_L = 100Ω, - 3dB	1	7	-	kHz
	Response time	Rise time	t_r	V_{CE} = 2V, I_C = 20mA, R_L = 100Ω	-	100	300	μs
		Fall time	t_f		-	20	100	μs

Fig. 1 Forward Current vs. Ambient Temperature

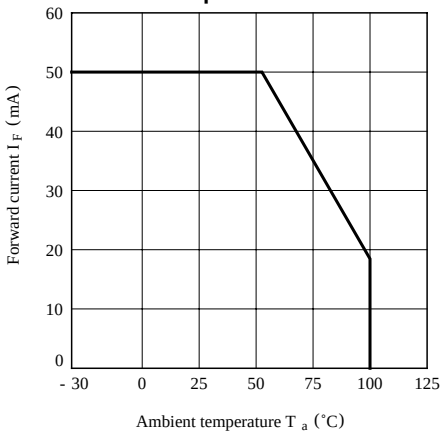


Fig. 2 Collector Power Dissipation vs. Ambient Temperature

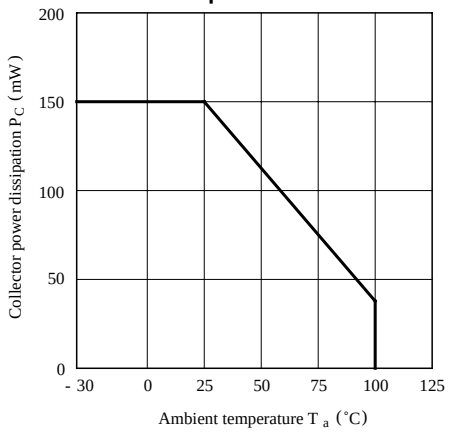


Fig. 3 Peak Forward Current vs. Duty Ratio

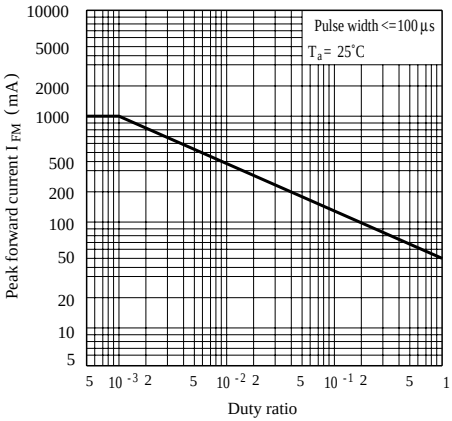


Fig. 4 Forward Current vs. Forward Voltage

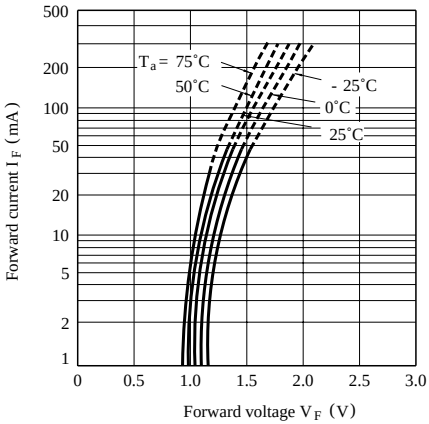


Fig. 5 Current Transfer Ratio vs. Forward Current

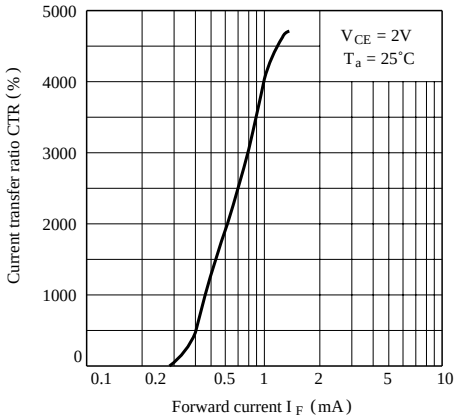


Fig. 6 Collector Current vs. Collector-emitter Voltage

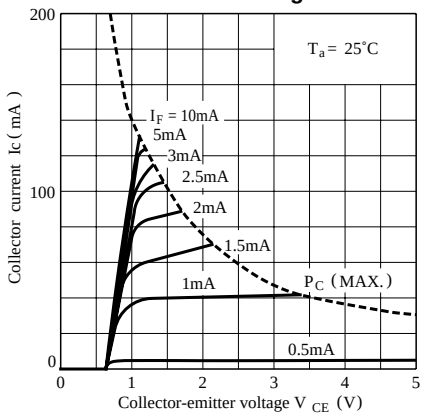


Fig. 7 Relative Current Transfer Ratio vs. Ambient Temperature

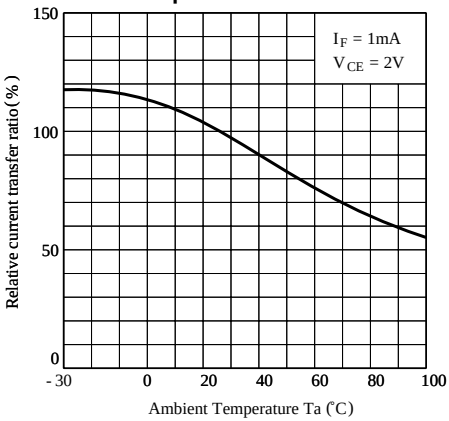


Fig. 8 Collector-emitter Saturation Voltage vs. Ambient Temperature

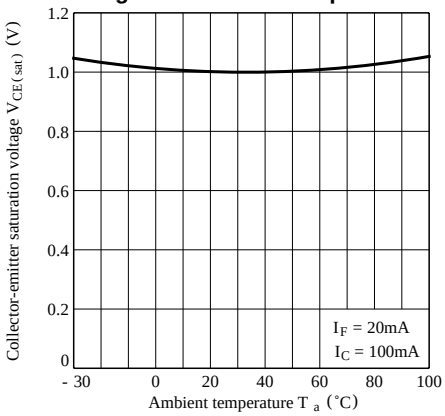


Fig. 9 Collector Dark Current vs. Ambient Temperature

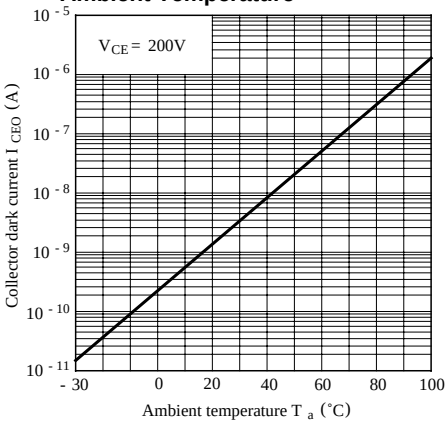


Fig.10 Response Time vs. Load Resistance

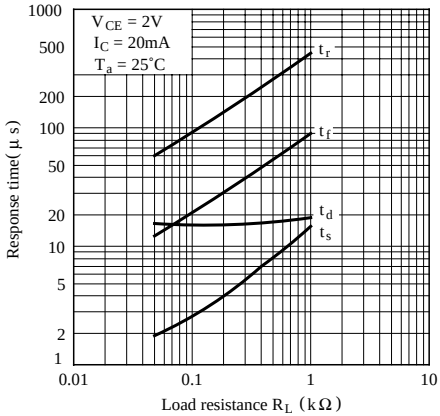


Fig.11 Frequency Response

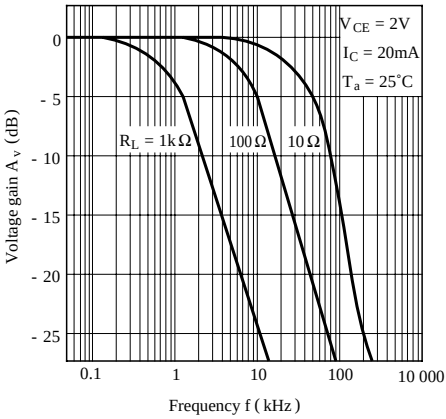
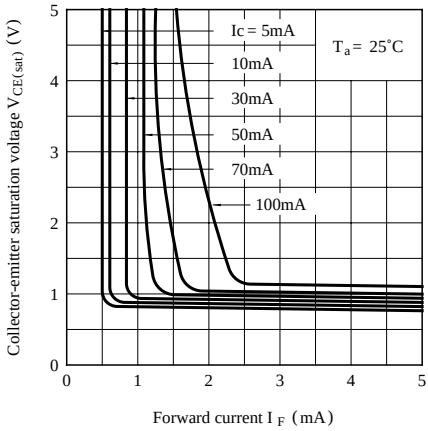


Fig.12 Collector-emitter Saturation Voltage vs. Forward Current



● Please refer to the chapter "Precautions for Use."

NOTICE

- The circuit application examples in this publication are provided to explain representative applications of SHARP devices and are not intended to guarantee any circuit design or license any intellectual property rights. SHARP takes no responsibility for any problems related to any intellectual property right of a third party resulting from the use of SHARP's devices.
- Contact SHARP in order to obtain the latest device specification sheets before using any SHARP device. SHARP reserves the right to make changes in the specifications, characteristics, data, materials, structure, and other contents described herein at any time without notice in order to improve design or reliability. Manufacturing locations are also subject to change without notice.
- Observe the following points when using any devices in this publication. SHARP takes no responsibility for damage caused by improper use of the devices which does not meet the conditions and absolute maximum ratings to be used specified in the relevant specification sheet nor meet the following conditions:

(i) The devices in this publication are designed for use in general electronic equipment designs such as:
- Personal computers
- Office automation equipment
- Telecommunication equipment [terminal]
- Test and measurement equipment
- Industrial control
- Audio visual equipment
- Consumer electronics

(ii) Measures such as fail-safe function and redundant design should be taken to ensure reliability and safety when SHARP devices are used for or in connection with equipment that requires higher reliability such as:
- Transportation control and safety equipment (i.e., aircraft, trains, automobiles, etc.)
- Traffic signals
- Gas leakage sensor breakers
- Alarm equipment
- Various safety devices, etc.

(iii) SHARP devices shall not be used for or in connection with equipment that requires an extremely high level of reliability and safety such as:
- Space applications
- Telecommunication equipment [trunk lines]
- Nuclear power control equipment
- Medical and other life support equipment (e.g., scuba).

- Contact a SHARP representative in advance when intending to use SHARP devices for any "specific" applications other than those recommended by SHARP or when it is unclear which category mentioned above controls the intended use.
- If the SHARP devices listed in this publication fall within the scope of strategic products described in the Foreign Exchange and Foreign Trade Control Law of Japan, it is necessary to obtain approval to export such SHARP devices.
-
- Contact and consult with a SHARP representative if there are any questions about the contents of this publication.